

Title (en)
CONNECTOR FOR MAKING ELECTRICAL CONTACT AT SEMICONDUCTOR SCALES AND METHOD FOR FORMING SAME

Title (de)
VERBINDER ZUR HERSTELLUNG EINES ELEKTRISCHEN KONTAKTS AUF HALBLEITERMASSSTÄBEN UND VERFAHREN ZU SEINER BILDUNG

Title (fr)
CONNECTEUR PERMETTANT D'ETABLIR UN CONTACT ELECTRIQUE A DES ECHELLES DE SEMI-CONDUCTEURS ET PROCEDE DE FORMATION ASSOCIE

Publication
EP 1697989 A2 20060906 (EN)

Application
EP 04813215 A 20041207

Priority

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- US 73121303 A 20031208

Abstract (en)
[origin: WO2005057652A2] A connector, and method for forming same, for electrically connecting to pads formed on a semiconductor device includes a substrate and an array of contact elements of conductive material formed on the substrate. Each contact element includes a base portion attached to the top surface of the substrate and a curved spring portion extending from the base portion and having a distal end projecting above the substrate. The curved spring portion is formed to curve away from a plane of contact and has a curvature disposed to provide a controlled wiping action when engaging a respective pad of the semiconductor device.

IPC 8 full level
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Citation (search report)
See references of WO 2005057652A2

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